

Technical Data Sheet

Schulamid 66 MV3 H4 BLK968001



Polyamide 66

Product Description

medium viscosity PA 66, heat stabilized

Processing Method	Injection Molding
Attribute	Heat Stabilized; Medium Viscosity
Additive	Heat Stabilizer

Typical Properties	Nominal Value	Units	Test Method
Physical			
Density, (Method A)	1.14	g/cm ³	ISO 1183
Viscosity Number	145	cm ³ /g	ISO 307
Mechanical			
Tensile Stress at Yield			
(Type 1A, 50 mm/min)	90.0	MPa	ISO 527-2
(Type 1A, 50 mm/min) - Conditioned	70.0	MPa	ISO 527-2
Tensile Strain at Yield			
(Type 1A, 50 mm/min)	4.0	%	ISO 527-2
(Type 1A, 50 mm/min) - Conditioned	15	%	ISO 527-2
Tensile Modulus			
(1 mm/min, Type 1A)	3000	MPa	ISO 527-1
(1 mm/min, Type 1A) - Conditioned	1500	MPa	ISO 527-1
Impact			
Charpy Impact Strength - Notched			
(23 °C, Type 1, Edgewise, Notch A)	9.0	kJ/m ²	ISO 179
(-30 °C, Type 1, Edgewise, Notch A)	7.0	kJ/m ²	ISO 179
(23 °C, Type 1, Edgewise, Notch A) - Conditioned	13	kJ/m ²	ISO 179
(-30 °C, Type 1, Edgewise, Notch A) - Conditioned	5.0	kJ/m ²	ISO 179
Charpy Impact Strength - Unnotched			
(23 °C, Type 1, Edgewise)	150	kJ/m ²	ISO 179
(-30 °C, Type 1, Edgewise)	95	kJ/m ²	ISO 179
(23 °C, Type 1, Edgewise) - Conditioned	No Break		ISO 179
(-30 °C, Type 1, Edgewise) - Conditioned	No Break		ISO 179
Thermal			
Deflection Temperature Under Load Unannealed (0.45 MPa), (Flatwise)	225	°C	ISO 75-2/B
Deflection Temperature Under Load Unannealed (1.80 MPa), (Flatwise)	90.0	°C	ISO 75-2/A

Electrical

Volume Resistivity	>1.0E+13	ohm*m	IEC 62631-3-1
- Conditioned	10000000000 0	ohm*m	IEC 62631-3-1
Comparative Tracking Index (CTI)	600	V	IEC 60112
Surface Resistivity	>1.0E+15	ohm	IEC 60093

Flammable

Burning Rate			
(2.00 mm)	0.0	mm/min	ISO 3795
(2.00 mm)	0.0	mm/min	FMVSS 302
Glow Wire Flammability Index	925	°C	IEC 60695-2-12

UL Information

Flammability Classification, (0.75 mm)	V-2	IEC 60695-11-10, - 20
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Injection Parameters	Nominal Value	Units
Drying Time	3.0 to 4.0	hr
Drying Temperature	80	°C
Suggested Max Moisture	0.040 to 0.10	%
Processing (Melt) Temp	270 to 290	°C
Mold Temperature	60 to 100	°C